

isc N-Channel MOSFET Transistor

IPP60R099CP, IIPP60R099CP

• FEATURES

- Static drain-source on-resistance: $R_{DS(on)} \leq 0.099\Omega$
- Enhancement mode
- Fast Switching Speed
- 100% avalanche tested
- Minimum Lot-to-Lot variations for robust device performance and reliable operation

• DESCRIPTION

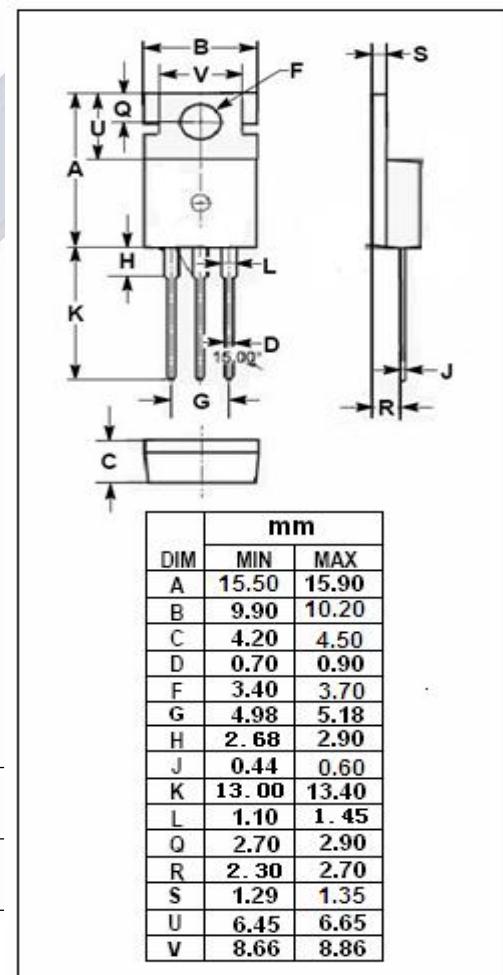
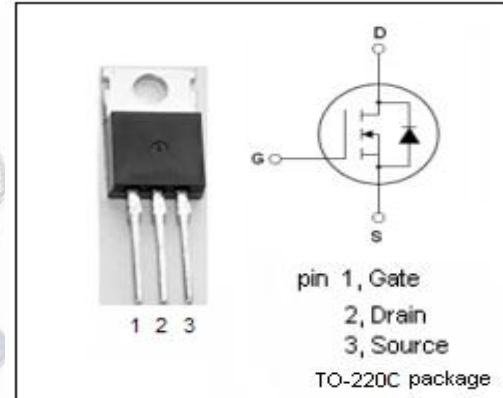
- Ultra low gate charge
- High peak current capability

• ABSOLUTE MAXIMUM RATINGS($T_a=25^\circ C$)

SYMBOL	PARAMETER	VALUE	UNIT
V_{DSS}	Drain-Source Voltage	600	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current-Continuous	31	A
I_{DM}	Drain Current-Single Pulsed	93	A
P_D	Total Dissipation @ $T_c=25^\circ C$	255	W
T_j	Max. Operating Junction Temperature	150	°C
T_{stg}	Storage Temperature	-55~150	°C

• THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
$R_{th(ch-c)}$	Channel-to-case thermal resistance	0.5	°C/W
$R_{th(ch-a)}$	Channel-to-ambient thermal resistance	62	°C/W



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ELECTRICAL CHARACTERISTICS

 $T_c=25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}; \text{ID} = 0.25\text{mA}$	600			V
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}; \text{ID} = 1.2\text{mA}$	2.5		3.5	V
$\text{R}_{\text{DS(on)}}$	Drain-Source On-Resistance	$\text{V}_{\text{GS}}=10\text{V}; \text{ID}=18\text{A}$			0.099	Ω
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=20\text{V}; \text{V}_{\text{DS}}=0\text{V}$			0.1	μA
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=600\text{V}; \text{V}_{\text{GS}}= 0\text{V}$			5	μA
V_{SD}	Diode forward voltage	$\text{I}_F=18\text{A}; \text{V}_{\text{GS}} = 0\text{V}$			1.2	V